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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	14KB (8K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1936-i-sp

Pin Diagram – 28-Pin SPDIP/SOIC/SSOP (PIC16(L)F1936)

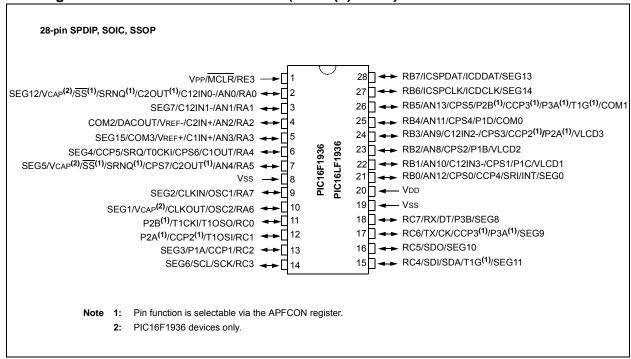


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TABLE 3-12: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets	
Bank 6	·											
300h ⁽²⁾	INDF0	Addressing (not a physic		ses contents o	of FSR0H/FSR	OL to address	data memor	/		xxxx xxxx	xxxx xxxx	
301h ⁽²⁾	INDF1		Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register) xxxx xxxx									
302h ⁽²⁾	PCL	Program Co	unter (PC) Le	ast Significant	Byte					0000 0000	0000 0000	
303h ⁽²⁾	STATUS	_	_	_	TO	PD	Z	DC	С	1 1000	q quuu	
304h ⁽²⁾	FSR0L	Indirect Data	a Memory Add	dress 0 Low Po	ointer					0000 0000	uuuu uuuu	
305h ⁽²⁾	FSR0H	Indirect Data	a Memory Add	dress 0 High P	ointer					0000 0000	0000 0000	
306h ⁽²⁾	FSR1L	Indirect Data	a Memory Add	dress 1 Low Po	ointer					0000 0000	uuuu uuuu	
307h ⁽²⁾	FSR1H	Indirect Data	a Memory Add	dress 1 High P	ointer					0000 0000	0000 0000	
308h ⁽²⁾	BSR	_	_	_		E	BSR<4:0>			0 0000	0 0000	
309h ⁽²⁾	WREG	Working Re	gister							0000 0000	uuuu uuuu	
30Ah ^(1, 2)	PCLATH	_	Write Buffer f	for the upper 7	bits of the Pro	ogram Counter	•			-000 0000	-000 0000	
30Bh ⁽²⁾	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000	
30Ch	_	Unimplemen	nted							_	_	
30Dh	_	Unimplemen	nted							_	_	
30Eh	_	Unimplemen	nted							_	_	
30Fh	_	Unimplemen	nted							_	_	
310h	_	Unimplemen	nted							_	_	
311h	CCPR3L	Capture/Cor	mpare/PWM F	Register 3 (LSI	3)					xxxx xxxx	uuuu uuuu	
312h	CCPR3H	Capture/Cor	mpare/PWM F	Register 3 (MS	B)					xxxx xxxx	uuuu uuuu	
313h	CCP3CON	P3M	<1:0>	DC3E	S<1:0>		CCP3M	<1:0>		0000 0000	0000 0000	
314h	PWM3CON	P3RSEN			P	23DC<6:0>				0000 0000	0000 0000	
315h	CCP3AS	CCP3ASE		CCP3AS<2:0>	>	PSS3A	C<1:0>	PSS3B	D<1:0>	0000 0000	0000 0000	
316h	PSTR3CON	_	_	_	STR3SYNC	STR3D	STR3C	STR3B	STR3A	0 0001	0 0001	
317h	_	Unimplemen	nted							_	_	
318h	CCPR4L	Capture/Cor	mpare/PWM F	Register 4 (LSF	3)					xxxx xxxx	uuuu uuuu	
319h	CCPR4H	Capture/Cor	mpare/PWM F	Register 4 (MS	B)					xxxx xxxx	uuuu uuuu	
31Ah	CCP4CON	_	_	DC4B	S<1:0>		CCP4M	<3:0>		00 0000	00 0000	
31Bh	_	Unimplemen	nted	•						_	_	
31Ch	CCPR5L	Capture/Cor	mpare/PWM F	Register 5 (LSI	3)					xxxx xxxx	uuuu uuuu	
31Dh	CCPR5H	Capture/Cor	mpare/PWM F	Register 5 (MS	B)					xxxx xxxx	uuuu uuuu	
31Eh	CCP5CON	_	_	DC5B	S<1:0>		CCP5M	<3:0>		00 0000	00 0000	
31Fh	_	Unimplemen	nted							_	_	

Legend: x = unknown, u = unchanged, q = value depends on condition, -= unimplemented, read as '0', x = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<14:8>, whose contents are transferred to the upper byte of the program counter.

- 2: These registers can be addressed from any bank.
- 3: These registers/bits are not implemented on PIC16(L)F1936 devices, read as '0'.
- 4: Unimplemented, read as '1'.

5.2.2.3 Internal Oscillator Frequency Adjustment

The 500 kHz internal oscillator is factory calibrated. This internal oscillator can be adjusted in software by writing to the OSCTUNE register (Register 5-3). Since the HFINTOSC and MFINTOSC clock sources are derived from the 500 kHz internal oscillator a change in the OSCTUNE register value will apply to both.

The default value of the OSCTUNE register is '0'. The value is a 5-bit two's complement number. A value of 0Fh will provide an adjustment to the maximum frequency. A value of 10h will provide an adjustment to the minimum frequency.

When the OSCTUNE register is modified, the oscillator frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred.

OSCTUNE does not affect the LFINTOSC frequency. Operation of features that depend on the LFINTOSC clock source frequency, such as the Power-up Timer (PWRT), Watchdog Timer (WDT), Fail-Safe Clock Monitor (FSCM) and peripherals, are *not* affected by the change in frequency.

5.2.2.4 LFINTOSC

The Low-Frequency Internal Oscillator (LFINTOSC) is an uncalibrated 31 kHz internal clock source.

The output of the LFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). Select 31 kHz, via software, using the IRCF<3:0> bits of the OSCCON register. See **Section 5.2.2.7** "Internal Oscillator Clock Switch Timing" for more information. The LFINTOSC is also the frequency for the Power-up Timer (PWRT), Watchdog Timer (WDT) and Fail-Safe Clock Monitor (FSCM).

The LFINTOSC is enabled by selecting 31 kHz (IRCF<3:0> bits of the OSCCON register = 000) as the system clock source (SCS bits of the OSCCON register = 1x), or when any of the following are enabled:

- Configure the IRCF<3:0> bits of the OSCCON register for the desired LF frequency, and
- FOSC<2:0> = 100, or
- Set the System Clock Source (SCS) bits of the OSCCON register to '1x'

Peripherals that use the LFINTOSC are:

- Power-up Timer (PWRT)
- Watchdog Timer (WDT)
- Fail-Safe Clock Monitor (FSCM)

The Low-Frequency Internal Oscillator Ready bit (LFIOFR) of the OSCSTAT register indicates when the LFINTOSC is running and can be utilized.

5.2.2.5 Internal Oscillator Frequency Selection

The system clock speed can be selected via software using the Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register.

The output of the 16 MHz HFINTOSC and 31 kHz LFINTOSC connects to a postscaler and multiplexer (see Figure 5-1). The Internal Oscillator Frequency Select bits IRCF<3:0> of the OSCCON register select the frequency output of the internal oscillators. One of the following frequencies can be selected via software:

- 32 MHz (requires 4X PLL)
- 16 MHz
- 8 MHz
- 4 MHz
- 2 MHz
- 1 MHz500 kHz (Default after Reset)
- 250 kHz
- 125 kHz
- 62.5 kHz
- 31.25 kHz

Note:

31 kHz (LFINTOSC)

Following any Reset, the IRCF<3:0> bits of the OSCCON register are set to '0111' and the frequency selection is set to 500 kHz. The user can modify the IRCF bits to select a different frequency.

The IRCF<3:0> bits of the OSCCON register allow duplicate selections for some frequencies. These duplicate choices can offer system design trade-offs. Lower power consumption can be obtained when changing oscillator sources for a given frequency. Faster transition times can be obtained between frequency changes that use the same oscillator source.

6.10 Determining the Cause of a Reset

Upon any Reset, multiple bits in the STATUS and PCON register are updated to indicate the cause of the Reset. Table 6-3 and Table 6-4 show the Reset conditions of these registers.

TABLE 6-3: RESET STATUS BITS AND THEIR SIGNIFICANCE

STKOVF	STKUNF	RMCLR	RI	POR	BOR	то	PD	Condition	
0	0	1	1	0	х	1	1	Power-on Reset	
0	0	1	1	0	х	0	х	Illegal, TO is set on POR	
0	0	1	1	0	х	х	0	Illegal, PD is set on POR	
0	0	1	1	u	0	1	1	Brown-out Reset	
u	u	u	u	u	u	0	u	WDT Reset	
u	u	u	u	u	u	0	0	WDT Wake-up from Sleep	
u	u	u	u	u	u	1	0	Interrupt Wake-up from Sleep	
u	u	0	u	u	u	u	u	MCLR Reset during normal operation	
u	u	0	u	u	u	1	0	MCLR Reset during Sleep	
u	u	u	0	u	u	u	u	RESET Instruction Executed	
1	u	u	u	u	u	u	u	Stack Overflow Reset (STVREN = 1)	
u	1	u	u	u	u	u	u	Stack Underflow Reset (STVREN = 1)	

TABLE 6-4: RESET CONDITION FOR SPECIAL REGISTERS⁽²⁾

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	0000h	1 1000	00 110x
MCLR Reset during normal operation	0000h	u uuuu	uu 0uuu
MCLR Reset during Sleep	0000h	1 0uuu	uu 0uuu
WDT Reset	0000h	0 uuuu	uu uuuu
WDT Wake-up from Sleep	PC + 1	0 0uuu	uu uuuu
Brown-out Reset	0000h	1 1uuu	00 11u0
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	1 Ouuu	uu uuuu
RESET Instruction Executed	0000h	u uuuu	uu u0uu
Stack Overflow Reset (STVREN = 1)	0000h	u uuuu	1u uuuu
Stack Underflow Reset (STVREN = 1)	0000h	u uuuu	u1 uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and Global Enable bit (GIE) is set, the return address is pushed on the stack and PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

2: If a Status bit is not implemented, that bit will be read as '0'.

7.6.6 PIR2 REGISTER

Legend:

R = Readable bit

u = Bit is unchanged

The PIR2 register contains the interrupt flag bits, as shown in Register 7-6.

Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 7-6: PIR2: PERIPHERAL INTERRUPT REQUEST REGISTER 2

W = Writable bit

x = Bit is unknown

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0
OSFIF	C2IF	C1IF	EEIF	BCLIF	LCDIF	_	CCP2IF
bit 7							bit 0

Note:

U = Unimplemented bit, read as '0'

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set	'0' = Bit is cleared
bit 7	OSFIF: Oscillator Fail Interrupt Flag
	1 = Interrupt is pending
	0 = Interrupt is not pending
bit 6	C2IF: Comparator C2 Interrupt Flag
	1 = Interrupt is pending 0 = Interrupt is not pending
bit 5	C1IF: Comparator C1 Interrupt Flag
	1 = Interrupt is pending
	0 = Interrupt is not pending
bit 4	EEIF: EEPROM Write Completion Interrupt Flag bit
	1 = Interrupt is pending
	0 = Interrupt is not pending
bit 3	BCLIF: MSSP Bus Collision Interrupt Flag bit
	1 = Interrupt is pending
	0 = Interrupt is not pending
bit 2	LCDIF: LCD Module Interrupt Flag bit
	1 = Interrupt is pending
	0 = Interrupt is not pending
bit 1	Unimplemented: Read as '0'
bit 0	CCP2IF: CCP2 Interrupt Flag bit
	1 = Interrupt is pending
	0 = Interrupt is not pending

11.2 Using the Data EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). When variables in one section change frequently, while variables in another section do not change, it is possible to exceed the total number of write cycles to the EEPROM without exceeding the total number of write cycles to a single byte. Refer to the applicable Electrical Specifications Chapter. If this is the case, then a refresh of the array must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

11.2.1 READING THE DATA EEPROM MEMORY

To read a data memory location, the user must write the address to the EEADRL register, clear the EEPGD and CFGS control bits of the EECON1 register, and then set control bit RD. The data is available at the very next cycle, in the EEDATL register; therefore, it can be read in the next instruction. EEDATL will hold this value until another read or until it is written to by the user (during a write operation).

EXAMPLE 11-1: DATA EEPROM READ

```
BANKSEL EEADRL ;

MOVLW DATA_EE_ADDR ;

MOVWF EEADRL ; Data Memory ; Address to read

BCF EECON1, CFGS ; Deselect Config space
BCF EECON1, EEPGD; Point to DATA memory
BSF EECON1, RD ; EE Read

MOVF EEDATL, W ; W = EEDATL
```

Note: Data EEPROM can be read regardless of the setting of the CPD bit.

11.2.2 WRITING TO THE DATA EEPROM MEMORY

To write an EEPROM data location, the user must first write the address to the EEADRL register and the data to the EEDATL register. Then the user must follow a specific sequence to initiate the write for each byte.

The write will not initiate if the above sequence is not followed exactly (write 55h to EECON2, write AAh to EECON2, then set the WR bit) for each byte. Interrupts should be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. EEIF must be cleared by software.

11.2.3 PROTECTION AGAINST SPURIOUS WRITE

There are conditions when the user may not want to write to the data EEPROM memory. To protect against spurious EEPROM writes, various mechanisms have been built-in. On power-up, WREN is cleared. Also, the Power-up Timer (64 ms duration) prevents EEPROM write.

The write initiate sequence and the WREN bit together help prevent an accidental write during:

- · Brown-out
- · Power Glitch
- · Software Malfunction

11.2.4 DATA EEPROM OPERATION DURING CODE-PROTECT

Data memory can be code-protected by programming the $\overline{\text{CPD}}$ bit in the Configuration Word 1 (Register 5-1) to '0'.

When the data memory is code-protected, only the CPU is able to read and write data to the data EEPROM. It is recommended to code-protect the program memory when code-protecting data memory. This prevents anyone from replacing your program with a program that will access the contents of the data EEPROM.

11.4 Modifying Flash Program Memory

When modifying existing data in a program memory row, and data within that row must be preserved, it must first be read and saved in a RAM image. Program memory is modified using the following steps:

- Load the starting address of the row to be modified.
- Read the existing data from the row into a RAM image.
- Modify the RAM image to contain the new data to be written into program memory.
- Load the starting address of the row to be rewritten.
- 5. Erase the program memory row.
- Load the write latches with data from the RAM image.
- 7. Initiate a programming operation.
- 8. Repeat steps 6 and 7 as many times as required to reprogram the erased row.

11.5 User ID, Device ID and Configuration Word Access

Instead of accessing program memory or EEPROM data memory, the User ID's, Device ID/Revision ID and Configuration Words can be accessed when CFGS = 1 in the EECON1 register. This is the region that would be pointed to by PC<15> = 1, but not all addresses are accessible. Different access may exist for reads and writes. Refer to Table 11-2.

When read access is initiated on an address outside the parameters listed in Table 11-2, the EEDATH:EEDATL register pair is cleared.

TABLE 11-2: USER ID, DEVICE ID AND CONFIGURATION WORD ACCESS (CFGS = 1)

Address	Function	Read Access	Write Access
8000h-8003h	User IDs	Yes	Yes
8006h	Device ID/Revision ID	Yes	No
8007h-8008h	Configuration Words 1 and 2	Yes	No

EXAMPLE 11-3: CONFIGURATION WORD AND DEVICE ID ACCESS

```
This code block will read 1 word of program memory at the memory address:
 PROG_ADDR_LO (must be 00h-08h) data will be returned in the variables;
 PROG_DATA_HI, PROG_DATA_LO
 BANKSEL EEADRL
                           ; Select correct Bank
          PROG_ADDR_LO
 W-TV/OM
 MOVWF
          EEADRL
                          ; Store LSB of address
 CLRF
          EEADRH
                           ; Clear MSB of address
 BSF
          EECON1,CFGS
                          ; Select Configuration Space
          INTCON, GIE
 BCF
                           ; Disable interrupts
          EECON1,RD
                           ; Initiate read
 BSF
 NOP
                           ; Executed (See Figure 11-1)
 NOP
                           ; Ignored (See Figure 11-1)
          INTCON, GIE
 BSF
                           ; Restore interrupts
 MOVF
          EEDATL,W
                          ; Get LSB of word
                          ; Store in user location
 MOVWF
          PROG_DATA_LO
 MOVF
          EEDATH,W
                           ; Get MSB of word
 MOVWF
          PROG_DATA_HI
                           ; Store in user location
```

11.6 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM or program memory should be verified (see Example 11-6) to the desired value to be written. Example 11-6 shows how to verify a write to EEPROM.

EXAMPLE 11-6: EEPROM WRITE VERIFY

```
BANKSEL EEDATL ;

MOVF EEDATL, W ;EEDATL not changed ;from previous write

BSF EECON1, RD ;YES, Read the ;value written

XORWF EEDATL, W ;

BTFSS STATUS, Z ;Is data the same GOTO WRITE_ERR ;No, handle error ;Yes, continue
```

REGISTER 12-20: LATE: PORTE DATA LATCH REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-x/u	R/W-x/u	R/W-x/u
_	_	_	_	_	LATE2	LATE1	LATE0
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set '0' = Bit is cleared

bit 7-3 **Unimplemented**: Read as '0'

bit 2-0 LATE<2:0>: PORTE Output Latch Value bits⁽¹⁾

Note 1: Writes to PORTE are actually written to corresponding LATE register. Reads from PORTE register is return of actual I/O pin values.

REGISTER 12-21: ANSELE: PORTE ANALOG SELECT REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
_	_	_	_	_	ANSE2 ⁽²⁾	ANSE1 ⁽²⁾	ANSE0 ⁽²⁾
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 ANSE<2:0>: Analog Select between Analog or Digital Function on Pins RE<2:0>, respectively

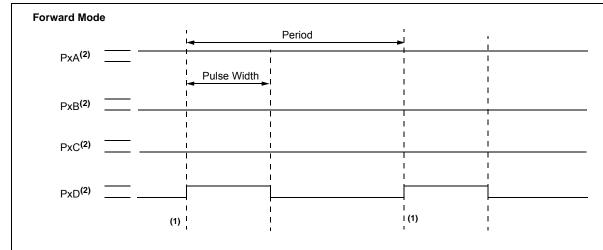
0 = Digital I/O. Pin is assigned to port or digital special function.

1 = Analog input. Pin is assigned as analog input⁽¹⁾. Digital input buffer disabled.

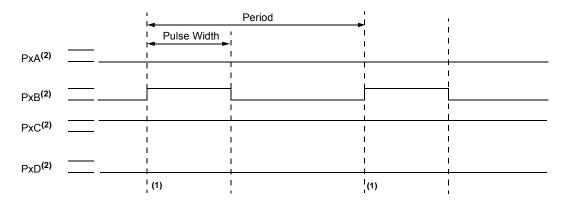
Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

2: ANSELE register is not implemented on the PIC16(L)F1936. Read as '0'

FIGURE 23-11: EXAMPLE OF FULL-BRIDGE PWM OUTPUT



Reverse Mode



Note 1: At this time, the TMRx register is equal to the PRx register.

2: Output signal is shown as active-high.

24.0 MASTER SYNCHRONOUS SERIAL PORT MODULE

24.1 Master SSP (MSSP) Module Overview

The Master Synchronous Serial Port (MSSP) module is a serial interface useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D converters, etc. The MSSP module can operate in one of two modes:

- · Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit (I²C[™])

The SPI interface supports the following modes and features:

- · Master mode
- · Slave mode
- · Clock Parity
- Slave Select Synchronization (Slave mode only)
- · Daisy-chain connection of slave devices

Figure 24-1 is a block diagram of the SPI interface module.

FIGURE 24-1: MSSP BLOCK DIAGRAM (SPI MODE)

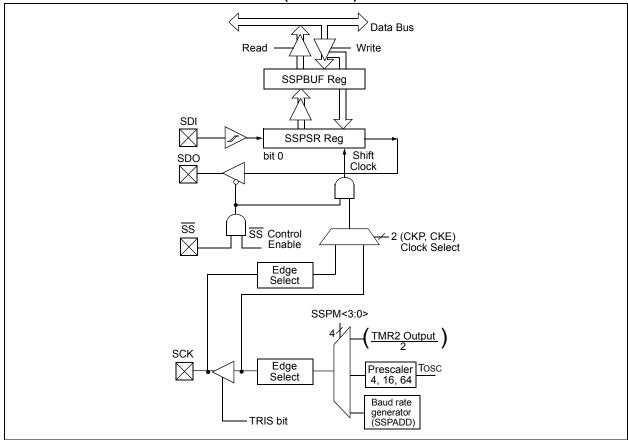


TABLE 26-3: SUMMARY OF REGISTERS ASSOCIATED WITH CAPACITIVE SENSING

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
ANSELA	_	_	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	134
ANSELB	_	_	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	139
ANSELD	ANSD7	ANSD6	ANSD5	ANSD4	ANSD3	ANSD2	ANSD1	ANSD0	146
CPSCON0	CPSON	_	_	_	CPSRN	CPSRNG<1:0> CPSOUT T0XCS			323
CPSCON1	_	_	_	_		CPSCI	H<3:0>		324
OPTION_REG	WPUEN	INTEDG	TMR0CS	TMR0SE	PSA	PS2	PS1	PS0	193
T1CON	TMR1C	S<1:0>	T1CKP	S<1:0>	T10SCEN	T1SYNC	_	TMR10N	203
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	133
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	138
TRISD	TRISD7	TRISD6	TRISD5	TRISD4	TRISD3	TRISD2	TRISD1	TRISD0	145

Legend: — = Unimplemented location, read as '0'. Shaded cells are not used by the CPS module.

27.1 LCD Registers

The module contains the following registers:

- LCD Control register (LCDCON)
- LCD Phase register (LCDPS)
- LCD Reference Ladder register (LCDRL)
- LCD Contrast Control register (LCDCST)
- LCD Reference Voltage Control register (LCDREF)
- Up to 3 LCD Segment Enable registers (LCDSEn)
- · Up to 12 LCD data registers (LCDDATAn)

TABLE 27-1: LCD SEGMENT AND DATA REGISTERS

	# of LCD Registers			
Device	Segment Enable	Data		
PIC16(L)F1936	2	8		
PIC16(L)F1934/7	3	12		

The LCDCON register (Register 27-1) controls the operation of the LCD driver module. The LCDPS register (Register 27-2) configures the LCD clock source prescaler and the type of waveform; Type-A or Type-B. The LCDSEn registers (Register 27-5) configure the functions of the port pins.

The following LCDSEn registers are available:

- LCDSE0 SE<7:0>
- LCDSE1 SE<15:8>
- LCDSE2 SE<23:16>(1)

Note 1: PIC16(L)F1934/7 only.

Once the module is initialized for the LCD panel, the individual bits of the LCDDATAn registers are cleared/set to represent a clear/dark pixel, respectively:

- LCDDATA0 SEG<7:0>COM0
- LCDDATA1 SEG<15:8>COM0
- LCDDATA2 SEG<23:16>COM0⁽¹⁾
- LCDDATA3 SEG<7:0>COM1
- LCDDATA4 SEG<15:8>COM1
- LCDDATA5 SEG<23:16>COM1⁽¹⁾
- LCDDATA6 SEG<7:0>COM2
- LCDDATA7 SEG<15:8>COM2
- LCDDATA8 SEG<23:16>COM2⁽¹⁾
- LCDDATA9 SEG<7:0>COM3
- LCDDATA10 SEG<15:8>COM3
- LCDDATA11 SEG<23:16>COM3⁽¹⁾

Note 1: PIC16(L)F1934/7 only.

As an example, LCDDATAn is detailed in Register 27-6.

Once the module is configured, the LCDEN bit of the LCDCON register is used to enable or disable the LCD module. The LCD panel can also operate during Sleep by clearing the SLPEN bit of the LCDCON register.

30.2 DC Characteristics: PIC16(L)F1934/6/7-I/E (Industrial, Extended) (Continued)

PIC16LF1934/36/37			Operating temperature			litions (unless otherwise stated) $-40^{\circ}C \leq TA \leq +85^{\circ}C \text{ for industrial}$ $-40^{\circ}C \leq TA \leq +125^{\circ}C \text{ for extended}$			
PIC16F1934/36/37			Operating temperature -4			tions (unless otherwise stated) -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended			
Param	Device Characteristics	Min.	Тур†	Max.	Units	Conditions			
No.						VDD	Note		
	Supply Current (IDD) ^{(1,}	2)							
D013		_	50	100	μА	1.8	Fosc = 500 kHz		
		_	85	150	μΑ	3.0	EC Oscillator Low-Power mode		
D013		_	70	120	μΑ	1.8	Fosc = 500 kHz		
		_	115	170	μΑ	3.0	EC Oscillator Low-Power mode (Note 5)		
		_	120	200	μΑ	5.0			
D014		_	400	550	μА	1.8	Fosc = 4 MHz		
		_	700	1100	μΑ	3.0	EC Oscillator mode Medium Power mode		
D014		_	430	650	μА	1.8	Fosc = 4 MHz		
		_	720	1000	μΑ	3.0	EC Oscillator mode (Note 5) Medium Power mode		
		_	850	1200	μΑ	5.0			
D015			5.3	6.2	mA	3.0	Fosc = 32 MHz EC Oscillator High-Power mode		
		_	6.3	7.5	mA	3.6	, and the second		
D015		_	5.3	6.5	mA	3.0	FOSC = 32 MHz		
		_	5.4	7.5	mA	5.0	EC Oscillator High-Power mode (Note 5)		
D016)16	5	12	μА	1.8	Fosc = 32 kHz, LFINTOSC mode (Note 4)			
		_	8	16	μΑ	3.0	-40°C ≤ TA ≤ +85°C		
D016		_	27	70	μΑ	1.8	Fosc = 32 kHz, LFINTOSC mode		
		_	34	80	μΑ	3.0	(Note 4, Note 5) -40°C ≤ TA ≤ +85°C		
		_	36	90	μΑ	5.0			

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.
- **3:** For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.
- 4: FVR and BOR are disabled.
- 5: 0.1 μF capacitor on VCAP (RA0).
- 6: 8 MHz crystal oscillator with 4x PLL enabled.

30.3 DC Characteristics: PIC16(L)F1934/6/7-I/E (Power-Down)

PIC16LF1934/36/37			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended						
PIC16F1934/36/37			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended						
Param No.	Device Characteristics	Min.	Typt		Max. +125°C	Units		Conditions	
	Barren darren Barra Crimana	(100)(2)		100 0	1.20 0		VDD	Note	
D023	Power-down Base Current	(IPD)\-/	0.06	1.0	8.0	μА	1.8	WDT, BOR, FVR, and T10SC	
D023			0.08	2.0	9.0	μА	3.0	disabled, all Peripherals Inactive	
D023			21	55	63	μА	1.8	WDT, BOR, FVR, and T1OSC	
D023			25	58	78	μА	3.0	disabled, all Peripherals Inactive	
		_	27	60	88	μА	5.0		
D024		_	0.5	4.0	9.0	μА	1.8	LPWDT Current (Note 1)	
		_	0.8	5.0	10	μА	3.0		
D024		_	23	57	65	μA	1.8	LPWDT Current (Note 1)	
		_	26	59	80	μΑ	3.0	·	
		_	28	61	90	μА	5.0		
D025		_	15	28	30	μА	1.8	FVR current	
		_	15	30	33	μА	3.0	1	
D025		_	38	96	100	μΑ	1.8	FVR current (Note 4)	
		_	45	110	120	μΑ	3.0		
		_	90	140	155	μА	5.0		
D026		_	13	25	28	μА	3.0	BOR Current (Note 1)	
D026		_	40	110	120	μΑ	3.0	BOR Current (Note 1, Note 4)	
		_	87	140	155	μΑ	5.0		
D027		_	0.6	5.0	9.0	μΑ	1.8	T1OSC Current (Note 1)	
		_	1.8	7.0	12	μА	3.0		
D027		_	22	57	60	μА	1.8	T1OSC Current (Note 1)	
		_	29	62	70	μА	3.0		
	There is a second to the second	_	35	66	85	μА	5.0		

- * These parameters are characterized but not tested.
- † Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max values should be used when calculating total current consumption.
 - 2: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD.
 - 3: A/D oscillator source is FRC.
 - 4: 0.1 μF capacitor on VCAP (RA0).

30.5 Memory Programming Requirements

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$					
Param No.	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions	
		Program Memory Programming Specifications						
D110	VIHH	Voltage on MCLR/VPP/RE3 pin	8.0	_	9.0	V	(Note 3, Note 4)	
D111	IDDP	Supply Current during Programming	_	_	10	mA		
D112		VDD for Bulk Erase	2.7	_	V _{DD} max.	V		
D113	VPEW	VDD for Write or Row Erase	V _{DD} min.	_	V _{DD} max.	V		
D114	IPPPGM	Current on MCLR/VPP during Erase/ Write	_	_	1.0	mA		
D115	IDDPGM	Current on VDD during Erase/Write	_		5.0	mA		
		Data EEPROM Memory						
D116	ED	Byte Endurance	100K	_	_	E/W	-40°C to +85°C	
D117	VDRW	VDD for Read/Write	V _{DD} min.	_	V _{DD} max.	V		
D118	TDEW	Erase/Write Cycle Time	_	4.0	5.0	ms		
D119	TRETD	Characteristic Retention	_	40	_	Year	Provided no other specifications are violated	
D120	TREF	Number of Total Erase/Write Cycles before Refresh ⁽²⁾	1M	10M	_	E/W	-40°C to +85°C	
		Program Flash Memory						
D121	EP	Cell Endurance	10K	_		E/W	-40°C to +85°C (Note 1)	
D122	VPR	VDD for Read	V _{DD} min.	_	V _{DD} max.	V		
D123	Tıw	Self-timed Write Cycle Time		2	2.5	ms		
D124	TRETD	Characteristic Retention	_	40	_	Year	Provided no other specifications are violated	

[†] Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1: Self-write and Block Erase.
 - 2: Refer to **Section 11.2 "Using the Data EEPROM"** for a more detailed discussion on data EEPROM endurance.
 - **3:** Required only if single-supply programming is disabled.
 - **4:** The MPLAB ICD 2 does not support variable VPP output. Circuitry to limit the ICD 2 VPP voltage must be placed between the ICD 2 and target system when programming or debugging with the ICD 2.

FIGURE 30-16: SPI MASTER MODE TIMING (CKE = 0, SMP = 0)

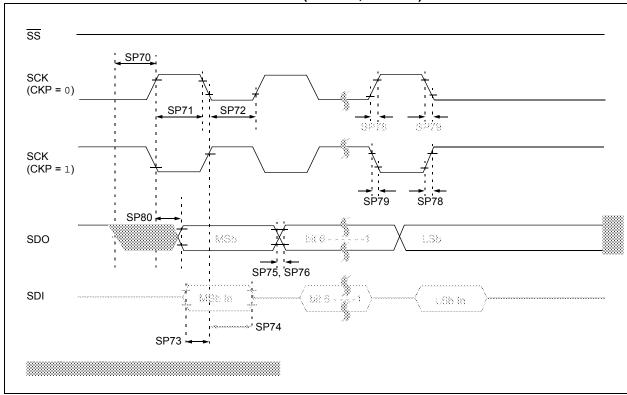


FIGURE 30-17: SPI MASTER MODE TIMING (CKE = 1, SMP = 1)

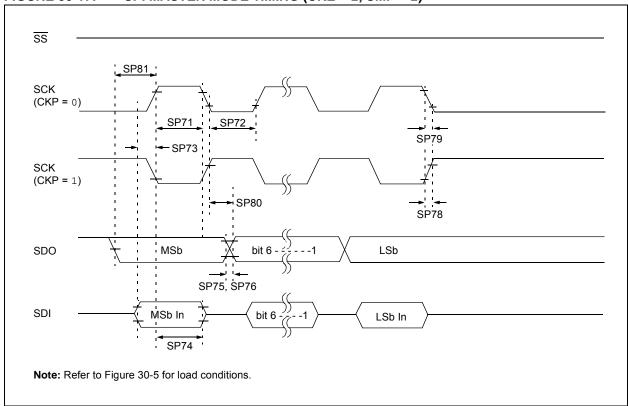


FIGURE 31-35: PIC16F1937 EC OSCILLATOR, HIGH-POWER MODE, Fosc = 32 MHz

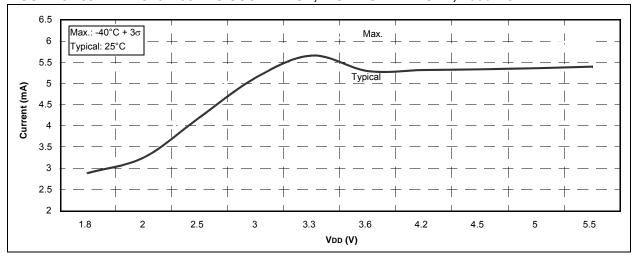


FIGURE 31-36: PIC16LF1937 EC OSCILLATOR, MEDIUM-POWER MODE, Fosc = 4 MHz

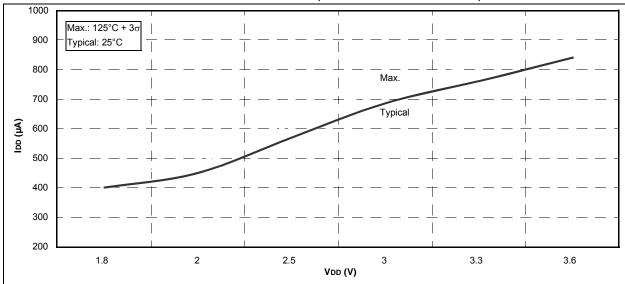
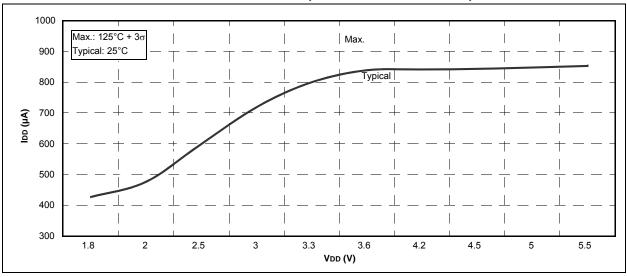


FIGURE 31-37: PIC16F1937 EC OSCILLATOR, MEDIUM-POWER MODE, Fosc = 4 MHz



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